Reprochem is able to offer and supply to our customers a full range of chemicals and consumables for the plating department. Additives for copper, for chrome, alkaline, aluminium. All developed with our own formulas.

**DEGREASING**

- **DEGREASING PASTE “GL”**
  Degreasing and Polishing paste for Copper surface. It contains a water based lubricant for application also by mechanical system.

- **DEGREASING POLISHING Paste “L”, “LN”**
  Degreasing and Polishing paste for Copper surface. It contains a polishing powder that allows a strong deoxidation.

- **DEGREASING POLISHING PASTE “RD”**
  Degreasing and Polishing paste for Copper surface. Especially used after dechroming operation, before cylinder rechroming. After treatment the Copper surface remains perfectly degreased and deoxidated.

- **DEGREASING AND PICKLING SOLUTION R-10**
  Degreasing and pickling solution suitable for Copper surface. It removes oil, grease and oxide. No further solvent or chemical degreasing process.

- **DEGREASING POLISHING Paste “RD73X, RD83A, RD83C”**
  Degreasing and Polishing paste for Copper surface with high abrasive power. Available with three different cutting power.

- **ANTEFOAM FOR EL DEGREASING**
  Product to prevent foam during the Electrolytic Degreasing operation.

- **DEGREASING SOLUTION CONC. 40 Bè TYPE VM**
  Concentrated Solution for Electrolytic Degreasing suitable for Copper and Chrome plating. To be diluted 1+7 with water. Suitable for Anodic and Cathodic process.

- **DEGREASING POWDER EL TYPE “N” AND “S”**
  Salt Mixture for Electrolytic Degreasing Solution for Copper and Chrome plating. Suitable for Anodic and Cathodic process.

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PLATING DEPARTMENT

ALKALINE COPPER
CU-ALC4 AND CU-ALC9
Concentrated alkaline Copper Solutions, Cyanide free, suitable for direct Copper deposition on steel cylinders. Working at low current density, allows an excellent adhesion of the following acid copper plating.

ACID STABILIZER FOR ALKALINE COPPER
Acidity corrector for pH control of Alkaline Copper plating.

NICKEL PLATING

NICKEL SALTS
Salt mixture for the preparation and maintenance of the solutions for Nickel plating on steel before acid copper deposition.

NICKEL SULPHATE
High purity Nickel salt for Nickel plating solution preparation.

STEEL ACTIVATOR
Pickling solution suitable for iron/steel surface preparation before Nickel plating, to improve the adhesion of the coating.

PICKLING SOLUTION
Pickling solution suitable especially for automatic plating lines, to improve the adhesion of Nickel on Steel, Copper on Nickel and Copper on Copper.

NICKEL ACTIVATOR
Solution suitable to remove any passivation (oxidation) from Nickel surface before Acid Copper plating. Improve Copper adhesion.
COPPER PLATING

HARD COPPER ADDITIVE CU-180
Copper Additive concentrated for Hard Copper Plating for mechanical engraving. The hardness can be adjusted from 190 to 230 HV and remains stable for a long time. Dosable by amperometric control. May work with and without Chloride. To dilute 1+9 for use.

HARD COPPER ADDITIVE CU-300 R
The additive CU 300 R is the newest technology in high speed Copper deposition. Monocomponent product, it allows a deposition speed of 30-35 A/dm² at 30-40°C working temperature. Very easy start up and maintenance. Chloride free. Product is concentrated: dilute 1+14.

CU HARD-D ADDITIVE POWDER
Powder Additive for hard Copper plating to be dissolved with water to have a ready to use additive solution.

HARD COPPER CU-200 AND
CU-214
Copper Additive for Hard Copper Plating for mechanical engraving. The hardness can be adjusted from 190 to 230 HV and remains stable for a long time. Dosable by amperometric control. It works without Chloride. To dilute 1+9 and 1+14 for use.

HARD COPPER ADDITIVE CU-HSD
Copper Plating with CU-HSD is a process for hard Copper deposition for printing cylinders. The Copper deposit is bright, with adjustable hardness (200-250 HV) stable over time. It works with Chloride and with high current density (till 40A/dm²). Up to 40 A/dm².

CU HARD-D ADDITIVE POWDER
Powder Additive for hard Copper plating to be dissolved with water to have a ready to use additive solution.

PURPOSE COPPER SULPHATE CRYSTALS
High purity Copper Sulphate salt for Hard Copper plating solution preparation. Low Chloride contents.

COPPER SHEET PLATING SOLUTION
1+9, 1+24, 1+30, FOR BALLARD
Concentrated Silver based solution to produce Copper sheet (Ballard) depositions on Copper base. Copper sheets (Ballard) easy to remove. Supplied with dilution 1+9, 1+24 and 1+30 with demineralized water.

SEPARATOR "P" POWDER
Organic powder product supplied in packs ready to be dissolved in water to obtain a solution to produce Copper sheet (Ballard) deposition on Copper base.

ACTIVE COAL FOR PLATING SOLUTION
High quality Active Coal for Copper solution depuration from organic pollution. No Chloride contents. Available in fine powder and in grain.
CR HS ADDITIVE FOR CHROME PLATING
This product is a catalyst which improves substantially the Chrome plating efficiency, increasing the deposition speed of about 50% and consequently reducing the plating time of 33%. More over it produces a Chrome deposit with high micro-crack structure that reduces the friction between the Chrome cylinder surface and the printing doctor blade.

ANTIFUME FOR CHROME
Foaming agent surfactant that, added in small quantity to the Chrome plating bath, reduces considerably (80-90%) the fume emissions. It keeps the tank and the suction pipes cleaner from fume recondensation.

CHROME ACID SOLUTION 25-37-40 Bè
Concentrated Chromic Acid Solutions for Chrome bath preparation and maintenance. Suitable also for automatic dosing in the tanks. May be supplied also with CR HS Chrome Additive and Antifume.

ALUMINIUM ACTIVATOR
Chemical Activator Coating for Aluminium for further Nickel or Alkaline Copper plating. Very important to have a good adhesion of the following metal plating.

ALUMINIUM PK SOLUTION
Pickling solution to remove the Aluminium oxide and passivate layer from the surface to allow a better Activator adhesion.
CONDUCTIVE GREASE
Grease with Copper micro-powder to improve the electrical contacts and consequently current transmission for the cylinder adaptors.

COLLOIDAL GRAPHITE
Graphite dispersion to seal holes and scratches on metal surfaces. The dry product is electrically conductive suitable for further depositions.

ANTIACID LACQUER
Peelable antiacid lacquer suitable to protect the adaptors and the cylinders edges during galvanic operations.

COLLOIDAL GRAPHITE
Graphite dispersion to seal holes and scratches on metal surfaces. The dry product of the lacquer is electrically conductive suitable for further depositions.